

IMPACT

TE Internal #: 2007793-1 High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT

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Connectors > PCB Connectors > Backplane Connectors > High Speed Backplane Connectors



Connector System: Board-to-Board Number of Positions: 144 Row-to-Row Spacing: 1.35 mm [.053 in] Mating Alignment: With

Mating Alignment Type: Keyed

Features



Product Type Features

| Signal Arrangement | Differential |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| PCB Connector Assembly Type | PCB Mount Header |
| Shroud Style | Partially Shrouded |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Number of Ground Positions | 48 |
| Number of Pairs | 48 |
| Stackable | No |
| Number of Signal Positions | 96 |
| Number of Positions | 144 |
| Number of Rows | 9 |
| Number of Columns | 16 |
| PCB Mount Orientation | Vertical |

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



| Impadance100 QOperating Voltage30 VACOperating Voltage30 VACSignal Characteristics20-25 Gb/sNumber of Differential Pairs per Column3Data Rate20-25 Gb/sBody Features100 ColorContact Mating Area LengthBlackPCB Contact Termination Area Plating Material Thickness76-152 µrn(30-60 µn)Contact Mating Area Length1.01 µn(30 µn)Contact TypePinContact Mating Area Plating Material Thickness76 µn(30 µn)Contact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material ThicknessGoldContact Mating Area Plating Material FinishMateriaContact Mating Area Plating Material FinishMateriaContact Mating Area Plating Material FinishMateriaContact Material MaterialGoldContact Material MaterialIninContact Current Rating (Max)Ja Pan(Ja Cance)Contact Current Rating (Max)Ja Karn(JAS ini)Contact Current Rating (Max)Ja Karn(JAS ini)Contact Current Rating (Max)Inrough Hole Press FitTermination Post & Tail LengthInrough Hole Press FitCurlea HardwareWithoutCurlea HardwareWithoutMating RetentionWithoutMaterial ThicknessWithoutContact Current Rating (Max)Inrough Hole Press FitCurrent Rating Material LengthMithoutMaterial ThicknessWit | | |
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| Contact Current Rating (Max).75 ATermination Features | PCB Contact Termination Area Plating Material | Tin |
| Termination Features Termination Post & Tail Length 1.4 mm[.055 in] Termination Method to Printed Circuit Board Through Hole - Press-Fit Wechanical Attachment Vithout Guide Hardware Without PCB Mount Retention With | Contact Base Material | Copper Alloy |
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| Termination Method to Printed Circuit Board Through Hole - Press-Fit Mechanical Attachment Vithout Guide Hardware Without Mating Retention Without PCB Mount Retention Without | Termination Features | |
| Mechanical Attachment With Guide Hardware Without Mating Retention Without PCB Mount Retention With | Termination Post & Tail Length | 1.4 mm[.055 in] |
| Guide HardwareWithMating RetentionWithoutPCB Mount RetentionWith | Termination Method to Printed Circuit Board | Through Hole - Press-Fit |
| Mating RetentionWithoutPCB Mount RetentionWith | Mechanical Attachment | |
| PCB Mount Retention With | Guide Hardware | With |
| | Mating Retention | Without |
| | PCB Mount Retention | With |
| PCB Mount Retention Type Action/Compliant Tail & Screw | PCB Mount Retention Type | Action/Compliant Tail & Screw |
| Mating Alignment With | Mating Alignment | With |

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



| Mating Alignment Type | Keyed |
|--|---|
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Number of Shrouded Sides | 2 |
| End Wall Location | Open |
| Housing Material | LCP - GF (Liquid Crystal Polymer) |
| Centerline (Pitch) | 1.9 mm[.075 in] |
| Dimensions | |
| Connector Length | 36.9 mm[1.453 in] |
| Connector Height | 24.6 mm[.969 in] |
| Connector Width | 16.7 mm[.657 in] |
| PCB Thickness (Recommended) | 1 mm |
| PCB Hole Diameter | .36 mm[.014 in] |
| Row-to-Row Spacing | 1.35 mm[.053 in] |
| Usage Conditions | |
| Operating Temperature Range | -55 – 85 °C[-67 – 185 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | CSA Certified, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Method | Box & Tube, Tube |
| Product Compliance For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2021 (211) |

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT



Does not contain REACH SVHC

Not Yet Reviewed for halogen content

Halogen Content

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



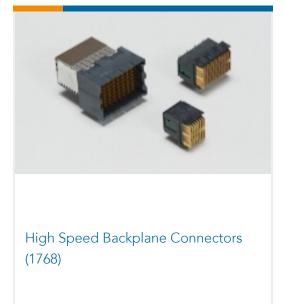
TE Part # 2007711-1 IMP100S,R,RA3P16C,UG,39



TOOL, SEAT 3 PR 16 COL, BP CONN



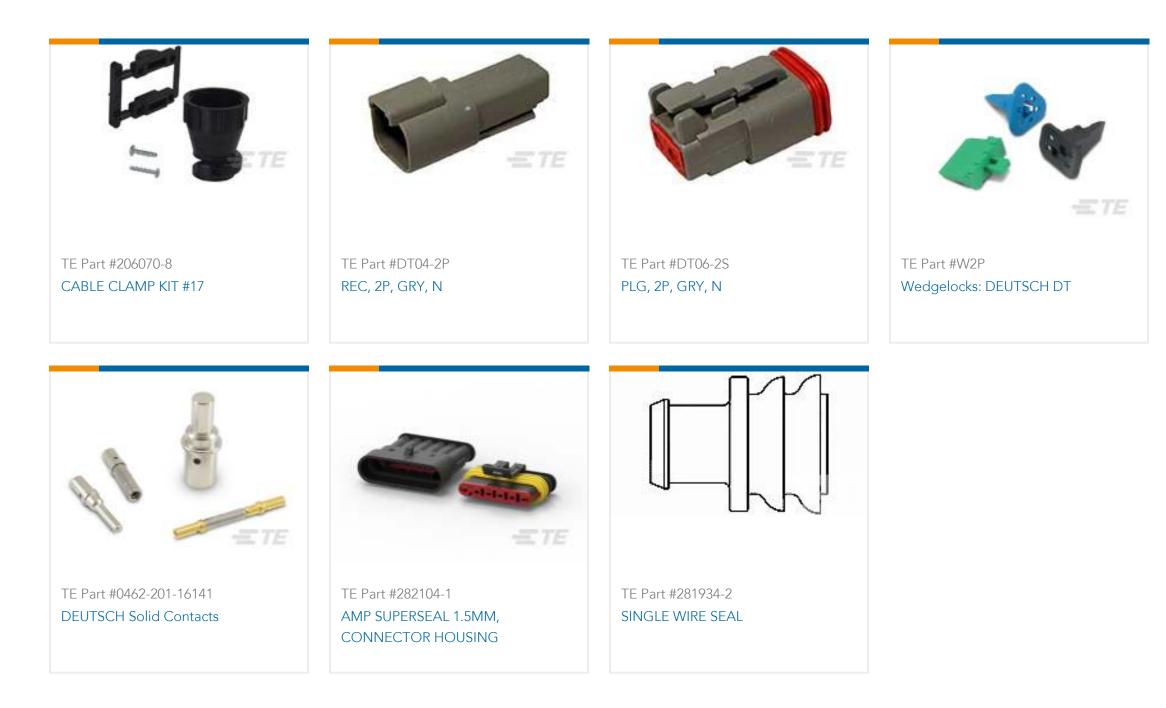
Also in the Series | IMPACT



Customers Also Bought

High Speed Backplane Connectors, 144 Position, Mating Alignment, Keyed Mating Alignment Type, 9 Row, 16 Column, PCB Mount Header, Vertical, IMPACT





Documents

CAD Files

Customer View Model

ENG_CVM_CVM_2007793-1_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2007793-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2007793-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the $\ensuremath{\text{Terms}}$ and $\ensuremath{\text{Conditions}}$ of use.

Datasheets & Catalog Pages 7-1773458-1_IMPACT_BACKPLANE_CONNECTOR_SYSTEM_CATALOG

English

Product Specifications

Application Specification

English

Agency Approvals Agency Approval Document

English